

**Delft University of Technology** 

# **Reliability of LED-based Systems**

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It helps to understand system performance and reduce decision risk during design and after the equipment is fielded. This approach models the root causes of failure such as fatigue, fracture, wear, and corrosion. An approach to the design and development of reliable product to prevent failure, based on the knowledge of root cause failure mechanisms. The concept is based on the understanding of the relationships between requirements and the physical characteristics of the product and their variation in the manufacturing processes, and the reaction of product elements and materials to loads (stressors) and interaction under loads and their influence on the fitness for use with respect to the use conditions and time.

The application of this concept to solid state lighting products is founded on the conviction that the failure of LED-based products is governed by optical, mechanical, electrical, thermal, and chemical processes. As such, potential problems in new and existing technologies can be identified and solved even before they occur, by understanding the possible failure mechanisms [14]. For LED-based systems, the concept is used, and results are carved in the so-called Failure Mode Handbook. This handbook consists of summary sheets for each newly discovered failure mode, see Figure 1, detailing out:

### ➢ Failure mode description

Short description of the failure mode, what is the observation? Accompanied, if possible, with a picture.

### Root cause / failure mechanism

What is the true cause of the failure mode, which physical mechanism is behind it?

# ➢ Solutions

What are possible solutions, how can one prevent the failure modes, what are the design rules to be obeyed?

## Lifetime model / acceleration

Under give testing conditions, what acceleration factors can be reached and what (lifetime) model is applicable.

### > Testing method

Following IEC62861 [13], or alike, which (accelerated) test provokes the failure mode?

Reference to technical documents and experts Internal or external document and/or experts are mentioned as touchpoints for further details.

A pre-filled example is shown in Figure 2: organic material degradation. This failure is well described in an open access review paper [15].



Figure 1: Summary sheet for failure modes, as part of the failure mode handbook.



Figure 2: Summary sheet for the failure mode organic material degradation.

Since 2011 the physics-of-failure concept is applied to LED-based products and systems. Both accelerated testing results prior to commercial release and actively monitoring field response (see the former paragraph) have yielded a total number of 88 unique failure modes since then. Figure 3 depicts the detection of new failure modes in a 10-year period. On average 10 new failure modes are discover per year. As it is expected, due to the growing maturity level of solid-state lighting products, this trend will once flatten out, the data is fitted with the Goel-Okumoto maturity growth model. This model is well-known for predicting the reliability of software [16]. Eventually, a total number of approximately 130 unique failure modes is to be discovered.



Figure 3: Number of unique failure modes as function of years.

Further data analysis is feasible as each unique failure modes is well described. Figure 4 depicts a pareto of

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the number of failure modes per product type. Examples are:

# ➢ LED package

Browning of LED silicone, Chip moisture corrosion, Dome melting / deforming, LED Vf shift, Silver mirror corrosion, Sticky silicone dome

### ➢ LED product

BOM outgassing, Color shift, Driver induced LED failures, Zener burn-out,

## ➢ LED system

*Battery failure, Software reliability, Surge issues, Water ingress* 

Table 1 lists the classification towards the component that failed and how it failed, either in a catastrophic manner or if any signs of degradation yielded to its failure. The numbers clarify the following:

- Degradation is a dominant failure mechanism within solid-state lighting products. This by itself is not a surprise as these products are intended for long-term usage.
- The components that contribute the most to product failure are the lightsource, the electronics and the mechanical construction.
- Failure modes in digital solutions (sensors, software) remain low and it is expected that this number will grow in the coming years due to the extension of the connected portfolio.
- Failure modes in the cooling system seem rare.
- For the optics, degradation is a leading failure mode with discoloration, yellowing, browning and corrosion as long-term events to occur.



Figure 4: Pareto for the number of failure mode vs product type.

Table 1: Failure mode classification towards component, catastrophic and degradation.

Component	Catastrophic	Degradation	Total
Lightsource	16	16	32
Optical materials	3	10	13
Electronics	12	11	23
Cooling system	0	2	2
Construction materials	5	10	15
Digital solution	2	1	3
Grand Total	39	49	88

### 3. Discussion & conclusions

In the past ten years we have witnessed a substantial change in the lighting industry. Traditional companies have changed their strategy and upcoming competition has pushed down prices for LED-based products considerably. LED penetration levels increased so as the diversity of commercially available replacement products. New processes and materials were introduced, and consequently new failure modes appeared. This trend has continued in the past four years as the lighting industry is getting connected and large amounts of user data is being analyzed. New components are needed to deliver this functionality (sensors, actuator IoT modules) and, as such, the diversity from an architectural point of view will also increase. In this paper, we have presented the currently known reliability and failures found in these solid-state lighting systems. It includes both degradation and catastrophic failure modes from observation towards a full description of its mechanism obtained by extensive use of acceleration tests using knowledge-based qualification methods. A total number of 88 failures modes are found, from which 60% are related to degradation. This indicates the importance of monitoring the degradation process in these products, as longer lifetimes and warrantees are industry targets. As such, gradually but slowly the term reliability in the lighting industry will be replaced by availability and 'smart' maintenance will distinguish good from bad products.

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2021 22nd International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE)

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